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| C & J | PRODUCTION SPECIFICATION | No. | 300 |
| | 3.96mm (.156") PITCH INTERCONNECTION SYSTEM | REV. | A |

一・ Suitable for use product :
This specification contains the test requirement that general performance of 300 Series Connector. (Housing, Wafer, Terminal)

二・ Part number :

W 3 0 0 V 0 3 T 0 0

Item:

H = Housing

W = Wafer

T = Terminal

Special Option :

00 = Standard .

Contact Plating :

O = Standard

T = Tin Plated

G = Gold Flash

Type:

V =180°

H =90°

S =Standard

N =Nonlock

B =Brass

P =Phosphor Bronze

No. of Circuits :

03 = 3 Position

三・ Detail product construction and dimensional :
See attached drawings .

四・ Test condition :
Room Temperature : 15 ~ 35 °C
Room humidity : 25 ~ 85 % (RH)
Ambient temperature rating : -25°C ~ +85°C .

五・ Performance :

1. Electrical Performance :

| ITEM | DESCRIPTION | TEST CONDITION | SPECIFICATION |
|------|----------------------------------|---|---|
| 1~1 | Appearance Examination | Inspected with naked eyes . | No crack, deformation nor discoloration |
| 1~2 | Voltage Rating Current Rating | — | 250V AC , DC 5 A AC , DC |
| 1~3 | Dielectric Withstanding Voltage | The test voltage shall be AC(r.m.s.) 1500V applied for one minute between any contact | Without break down |
| 1~4 | Insulation Resistance | DC 500V shall be applied between adjacent contacts of mated connector . | 1000 MΩ min . |
| 1~5 | Contact Resistance | Test current DC 10 mA. Open voltage DC 20 mV max. | 20 MΩ max. |

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| 2. Mechanical Performance : | | | | | |
| ITEM | DESCRIPTION | TEST CONDITION | | SPECIFICATION | |
| 2~1 | Applicable wire | Conductor construction size | | AWG # 18 ~ # 24 | |
| 2~2 | Crimp Tensile Strength | Pulling load shall be applied between correctly crimped contact and wire at speed 25 ± 3 mm per minute . | | #18: 8.0 kgf min #20: 6.5 kgf min #22: 4.0 kgf min #24: 3.0 kgf min | |
| 2~3 | Contact Insertion Force | Contact insertion into mating housing at speed 25 ± 3 mm per minute . | | 1.25 kgf max . | |
| 2~4 | Contact Retention Force | Pull out contact from mated housing at speed 25 ± 3 mm per minute . | | 3.0 kgf min . | |
| 2~5 | Insertion Force | Insertion into mating header at speed 25 ± 3 mm per minute . | | Refer item 4 . | |
| 2~6 | Withdrawal Force | Pull out from header at speed 25 ± 3 mm per minute . | | Refer item 4 . | |
| 2~7 | Post Retention Force | Pull out pin from insulator base at speed 25 ± 3 mm per minute . | | 3.0 kgf min . | |
| 2~8 | Vibration | Amplitude : 1.52mm . Frequency : 10-55-10 Hz / min . Direction : axis of up & down, axis of right & left, axis of front and back . Period: 2 hours flr each direction . | | Discontinuity : one micro second max . Appearance : no damage . | |
| 2~9 | Shock | Peak value is 50g , each 3 times for X, Y and Z directions | | Discontinuity : one micro second max . Appearance : no damage . | |
| 2~10 | Solderability | Solder temperature : 230 ± 5 °C . Immersion period : 3 ± 0.5 sec . | | Minimum : 75% of immersed area . | |
| 2~11 | Resistance to Soldering Heat | Solder temperature : 260 ± 5 °C . Immersion period : 5 ± 1 sec . | | No damage | |
| 2~12 | Durability | Housing with contact & header shall be mated coperated 100 cycles . | | Contact resistance less than twice of initial | |
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